

## SUBSTRATE POLISHING APPARATUS

### ABSTRACT

A substrate processing apparatus has a table on which a polishing surface for polishing a substrate is provided, and a discharge suction section which has a discharge port which communicates with a fluid supply source and through which a fluid is discharged to the polishing surface and a suction opening which communicates with a vacuum source and through which the fluid existing on the polishing surface is sucked.

Fig. 4